

APR 09 2005

PATENT  
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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| In re application of:<br>Kin Pui KWAN et al.<br>Serial No.: 09/802,678<br>Filing Date: March 9, 2001<br><b>For: LEADLESS PLASTIC CHIP<br/>CARRIER WITH ETCH BACK PAD<br/>SINGULATION</b> | Art Unit: 2826<br><br>Examiner: M. Tran |
|--|---|

DECLARATION UNDER 37 C.F.R. § 1.132

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

1. I, Neil MCLELLAN, hereby declare that I am an inventor in the present application.
2. I, Neil MCLELLAN, hereby declare that I invented all of the subject matter disclosed in U.S. Patent No. 6,545,347 and relied on in a prior art rejection of the claims in the presently pending U.S. Patent Application No. 09/802,678.
3. I, Neil MCLELLAN, hereby declare that I invented the common subject matter disclosed in U.S. Patent No. 6,545,347 and the presently pending U.S. Patent Application Serial No. 09/802,678.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

  
Neil MCLELLAN

2-2-05  
Date

Printer Friendly

09/799,968

ENHANCED LEADLESS CHIP CARRIER

## Application Data

|                         |                                    |                            |                                |
|-------------------------|------------------------------------|----------------------------|--------------------------------|
| Application Number:     | 09/799,968                         | Customer Number:           | -                              |
| Filing or 371 (c) Date: | 03-06-2001                         | Status:                    | Patented Case                  |
| Application Type:       | Utility                            | Status Date:               | 03-19-2003                     |
| Examiner Name:          | TRAN, MAI HUONG C                  | Location:                  | FILE REPOSITORY<br>(FRANCONIA) |
| Group Art Unit:         | 2818                               | Location Date:             | 2003-09-24 00:00:00.0          |
| Confirmation Number:    | 3435                               | Earliest Publication No:   | US 2002-0125559 A1             |
| Attorney Docket Number: | ASA017                             | Earliest Publication Date: | 09-12-2002                     |
| Class / Subclass:       | 257/690                            | Patent Number:             | 6,545,347                      |
| First Named Inventor:   | Neil Mclellan , Hong<br>Kong, (CN) | Issue Date of Patent:      | 04-08-2003                     |
| Title of Invention:     | ENHANCED LEADLESS CHIP CARRIER     |                            |                                |

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US 20020125559A1

(19) **United States**(12) **Patent Application Publication**

McLellan

(10) Pub. No.: US 2002/0125559 A1

(43) Pub. Date: Sep. 12, 2002

(54) **ENHANCED LEADLESS CHIP CARRIER**

(52) U.S. CL. .... 257/690

(76) Inventor: Neil McLellan, Hong Kong (CN)

Correspondence Address:  
**GALLAGHER & LATHROP**  
 601 CALIFORNIA ST  
 SUITE 1111  
 SAN FRANCISCO, CA 94108 (US)

(57) **ABSTRACT**

A plastic integrated circuit package includes a lead frame having numerous leads, a die attach pad and a ground ring. In one embodiment, the plastic integrated circuit package is provided as a plastic leadless chip carrier. Slots provided between the die attach pad and the ground ring provides support and prevent delamination from the plastic molding compound and enhanced moisture-resistance, thus resulting in a highly reliable integrated circuit package, even in the face of high temperature cycles, such as solder reflows.

(21) Appl. No.: 09/799,968

(22) Filed: Mar. 6, 2001

**Publication Classification**(51) Int. Cl.<sup>7</sup> ..... H01L 23/48